

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
SU-JEN SUNG		01/12/2014
RECEIVING PARTY DATA		
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6, SCIENCE-BASED INDUSTRIAL PARK	
City:	HSIN-CHU	
State/Country:	TAIWAN	
Postal Code:	300-77	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14157324	
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ATTORNEY DOCKET NUMBER:	24061.2637	
NAME OF SUBMITTER:	LINDA INGRAM	
Signature:	/Linda Ingram/	
Date:	01/16/2014	
Total Attachments: 2 source=2637_Assignment#page1.tif source=2637_Assignment#page2.tif		

ASSIGNMENT

WHEREAS, we,

(1) Su-Jen Sung of 9F., No.150, Sec. 1, Shengli 7th Street,
Zhubei City, Hsinchu County 302, Taiwan R.O.C.

have invented certain improvements in

**SYSTEMS AND METHODS FOR UNIFORM GAS FLOW
IN A DEPOSITION CHAMBER**

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X filed on January 16, 2014, and assigned application number 14/157,324; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Docket No.: 2013-0980 /24061.2637
Customer No.: 000042717

Inventor Name: Su-Jen Sung

Residence Address: 9F., No.150, Sec. 1, Shengli 7th Street
Zhubei City, Hsinchu County 302, Taiwan R.O.C.

✓
Dated: 01/12/14

✓ Su-Jen Sung
Inventor Signature